

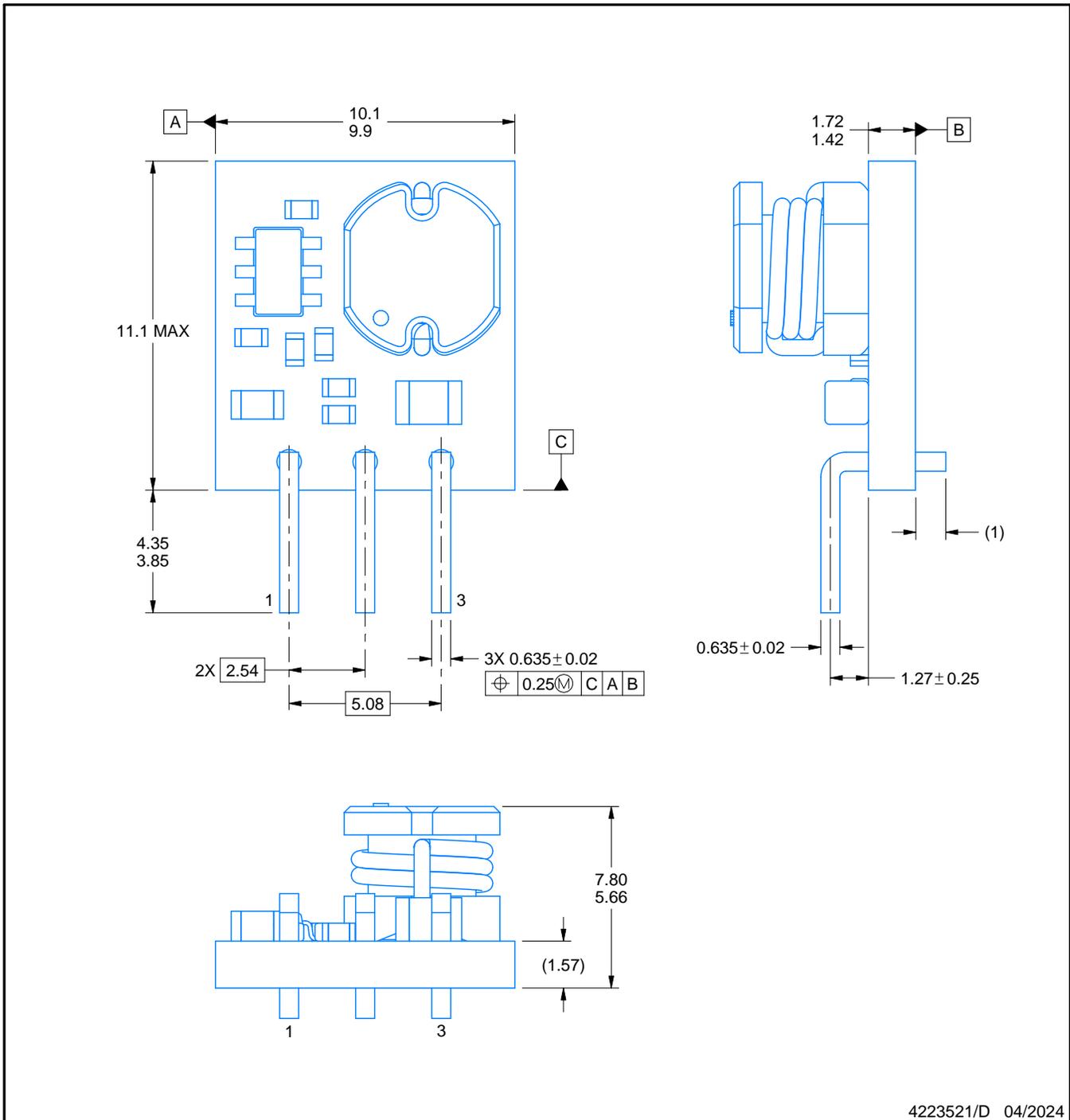
EAB0003A



PACKAGE OUTLINE

SIPMODULE - 11.1 mm max height

SYSTEM IN PACKAGE MODULE



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NOTES:

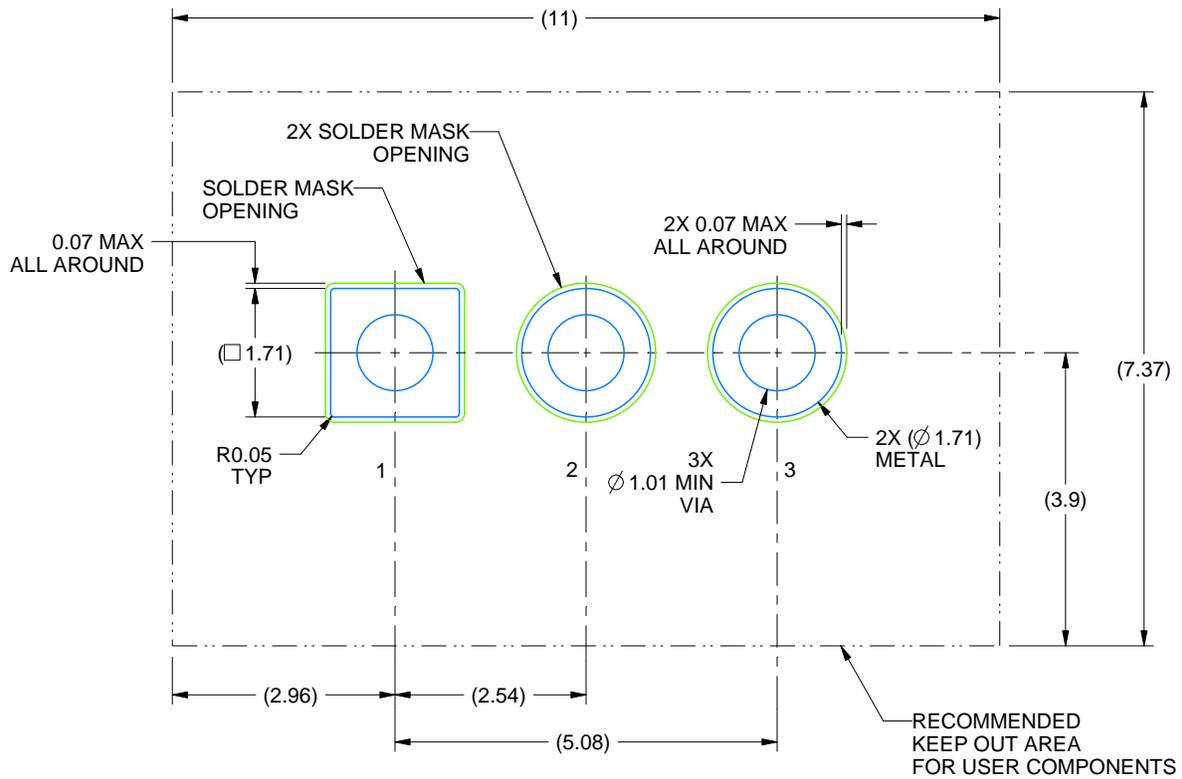
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Location, size and quantity of each component are for reference only and may vary.

EXAMPLE BOARD LAYOUT

EAB0003A

SIPMODULE - 11.1 mm max height

SYSTEM IN PACKAGE MODULE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE:10X

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REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2163130	02/07/2017	V. PAKU / T. LEQUANG
B	SIDE VIEW: ADD PIN CENTER TO PCB DIMENSION; REMOVE PIN EDGE TO PCB DIMENSION	2167747	08/14/2017	V. PAKU / K. SINCERBOX
C	4.35/3.85 WAS 4.1/3.5	2169958	11/20/2017	C. FERNANDEZ / K. SINCERBOX
D	1.27± 0.25 WAS 1.27± 0.025;	2208237	04/18/2024	A. VAZQUEZ / K. SINCERBOX

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